Manufacturer: TESAN ILETISIM A.S.

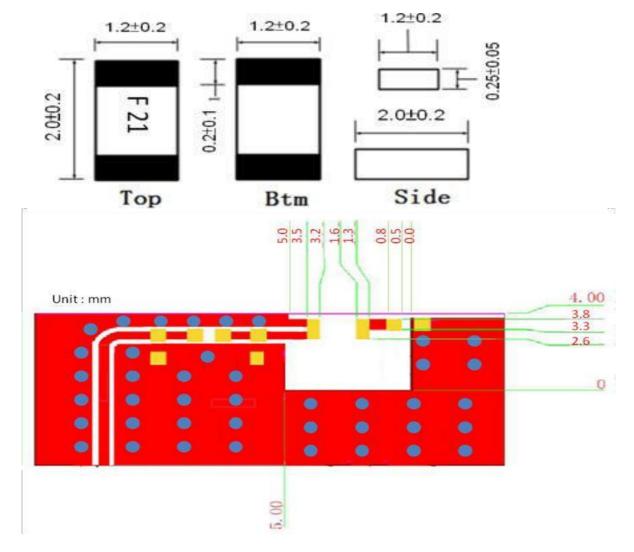
Features

- 1.Surface Mounted Devices with a small dimension of 2.0 x 1.25 x 0.25 mm³ meet future miniaturization trend.
- 2.Embedded and (Low Temperature Co-fired Ceramic) technology is able to future integrate with system design as well as beautifying the housing of final product.
- 3. High Stability in Temperature / Humidity Change

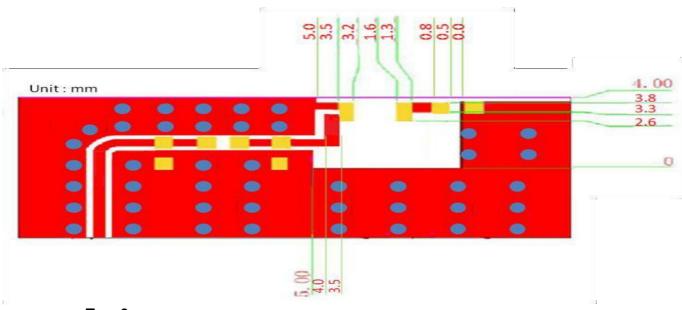
Applications

- 1. Bluetooth
- 2. Wireless LAN
- 3. HormRF
- 4. ISM band 2.4GHz wireless applications

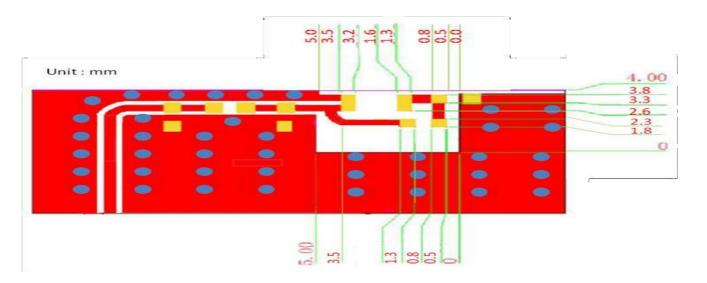
Dimensions (Unit: mm)



Type2:

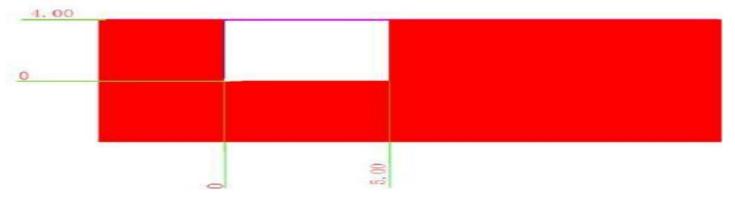


Type3:

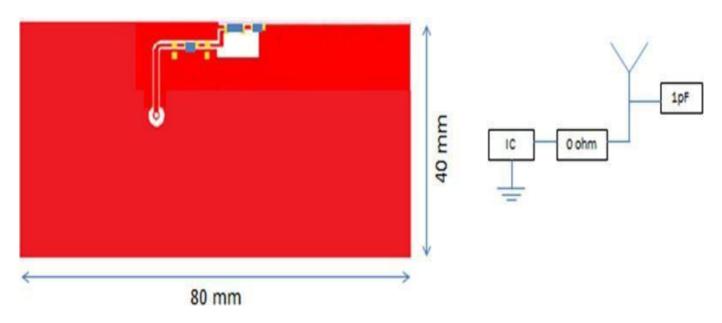


PCB Bottom View:





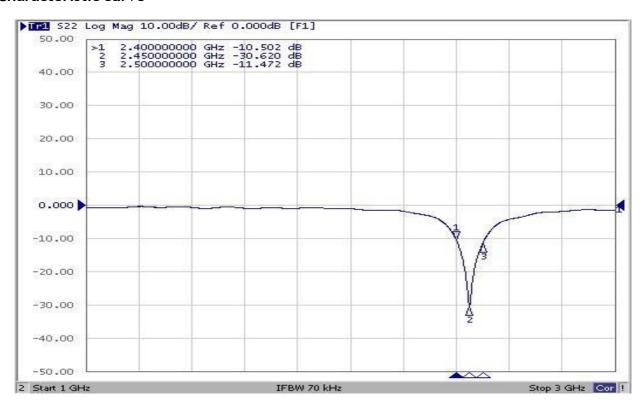
Evaluation Board and Matching Circuits



Electrical Characteristics

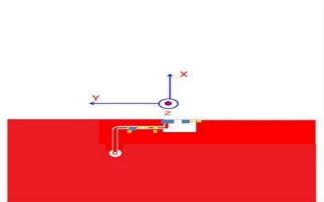
No.	Item	Specifications	
5.1	Working Central Frequency (After matching)	2450 MHz	
5.2	Band Width	86MHz typ.	
5.3	Peak Gain	1.72 dBi	
5.4	R.L.	≥7	
5.5	Polarization	Linear	
5.6	Azimuth Beam width	Omni-directional	
5.7	Impedance	50 Ω	

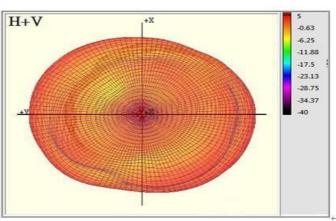
Characteristic curve

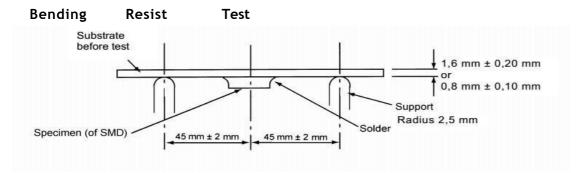


Radiation Pattern

Frequency(MHz)	2400	2450	2500
Efficiency (dB)	-2.82	-2.04	-2.41
Efficiency (%)	52.19	62.42	58,21
Gain (dBi)	1.72	1.41	1.63







Weld the product to the center part of the PCB with the thickness 1.6 ± 0.2 mm or 0.8 ± 0.1 mm as the illustration shows, and keep exerting force arrow-ward on it at speed of :1mm/S, and hold for 5 ± 1 S at the position of 1.5mm bending distance, so far, any peeling off of the product metal coating should not be detected.

Dependability Test

Temperature range	25±5°C
Relative Humidity range	55~75%RH
Operating Temperature range	-40°C~+85°C
Storage Temperature range	-40°C~+85°C

Vibration Resist

The device should fulfill the electrical specification after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

Drop Shock

The device should have no mechanical damage after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

Solder Heat Proof

The device should be satisfied after preheating at $120^{\circ}\text{C} \sim 150^{\circ}\text{C}$ for $120^{\circ}\text{C} = 150^{\circ}\text{C}$ for $120^{\circ}\text{C} = 10^{\circ}\text{C}$ for 120°

Adhesive Strength of Termination

The device have no remarkable damage or removal of the termination after horizontal force of $5N(\le 0603)$; 10N(>0603) with 10 ± 1 seconds.

Moisture Proof

The device should fulfill the electrical specification after exposed to the temperature 60±2 °C and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

High Temperature Endurance

The device should fulfill the electrical specification after exposed to temperature 85 ± 5 °C for 96 ± 2 hours and $1\sim2$ hours recovery time under normal temperature.

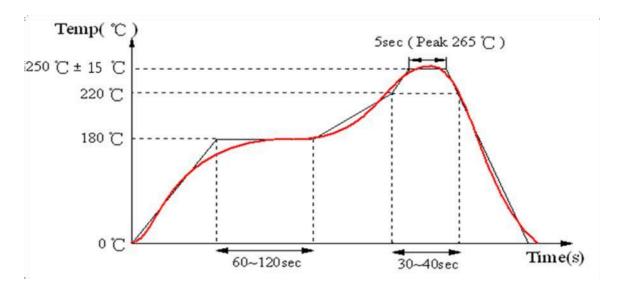
Low Temperature Endurance

The device should fulfill the electrical specification after exposed to the temperature -40 $^{\circ}$ C ±5 $^{\circ}$ C for 96±2 hours and to 2 hours recovery time under normal temperature.

Temperature Cycle Test

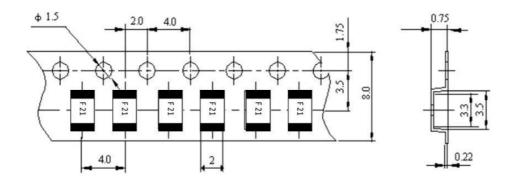
The device should fulfill the electrical specification after exposed to the low temperature -40°C and high temperature +85°C for 30 \pm 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

Reflow Soldering Standard Condition



Packaging and Dimensions (2012)

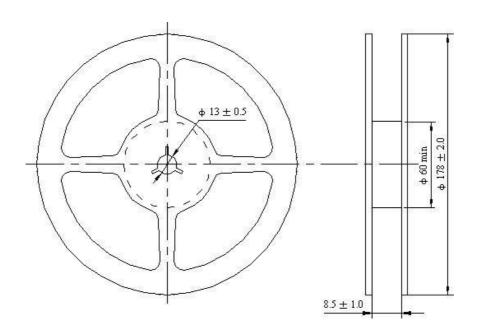
Plastic Tape



Remarks for Package

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.

Reel (6000 pcs/Reel)



Storage Period

Product should be used within six months of receipt.

MSL 1 / Storage Temperature Range : <30 degree C, Humidity : <85%RH